



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-11
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STL120N8F7	BSER*OD8FT52	A	SHENZHEN B/E	2016-01-11
Amount		UoM	Unit type	ST ECOPACK Grade
76.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5, 6, 0.8	12	FLAT	
Comment	Power FLAT 5x6 8L SINGLE			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BSER*OD8FT52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.850	mg	supplier	die	Silicon (Si)	7440-21-3		1.709	mg	923784	22487
				supplier	metallization	Aluminium (Al)	7429-90-5		0.047	mg	25405	618
				supplier	Passivation	Silicon Oxide	7631-86-9		0.028	mg	15135	368
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	2162	53
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.049	mg	26486	645
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	1081	26
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.011	mg	5946	145
				supplier	alloy	Copper (Cu)	7440-50-8		47.785	mg	974488	628750
Leadframe	Copper & its alloys	49.036	mg	supplier	alloy	Iron (Fe)	7439-89-6		1.124	mg	22922	14789
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.068	mg	1387	895
				supplier	alloy	Zinc (Zn)	7440-66-6		0.059	mg	1203	776
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	5.716	mg	925069	75211
Soft solder	Solder	6.179	mg	JIG - R	solder	Tin (Sn)	7440-31-5		0.154	mg	24923	2026
				supplier	solder	Silver (Ag)	7440-22-4		0.309	mg	50008	4066
				supplier	wire	Gold (Au)	7440-57-5		0.116	mg	1000000	1526
Encapsulation	Other Organic Materials	10.236	mg	supplier	mold compound	Silica, vitreous	60676-86-0		9.479	mg	926045	124724
				supplier	mold compound	epoxy resin	85954-11-6		0.409	mg	39957	5382
				supplier	mold compound	phenol resin	26834-02-6		0.307	mg	29992	4039
				supplier	mold compound	carbon black	1333-86-4		0.041	mg	4005	539
Connections coating	Solder	0.149	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	1961
Clip	Copper & its alloys	8.434	mg	supplier	alloy	Copper (Cu)	7440-50-8		8.434	mg	1000000	110974